



L7: Memory Basics and Timing



Acknowledgements:

- ➤ Nathan Ickes, Rex Min, Yun Wu
- ➤ Lecture material adapted from J. Rabaey, A. Chandrakasan, B. Nikolic, "Digital Integrated Circuits: A Design Perspective" Copyright 2003 Prentice Hall/Pearson.
- > Lecture notes prepared by Professor Anantha Chandrakasan



Memory Classification & Metrics



Read-Write Memory		Non-Volatile Read-Write Memory	Read-Only Memory (ROM)
Random Access	Non-Random Access	EPROM E ² PROM	Mask-Programmed
SRAM DRAM	FIFO LIFO	FLASH	

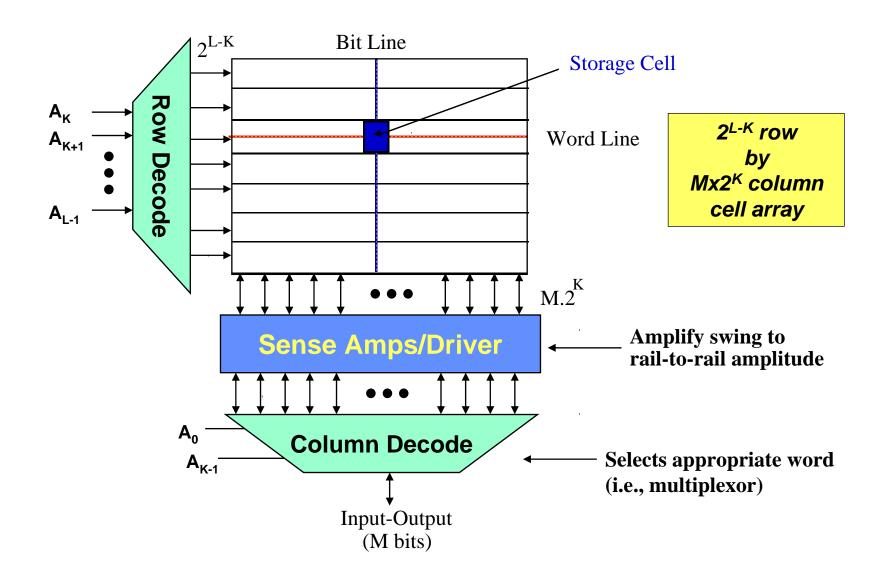
Key Design Metrics:

- 1. Memory Density (number of bits/μm²) and Size
- 2. Access Time (time to read or write) and Throughput
- 3. Power Dissipation



Memory Array Architecture



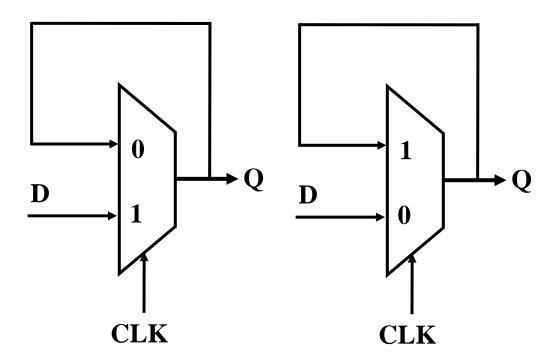




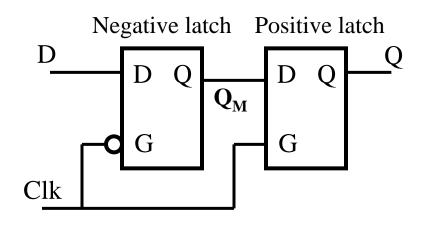
Latch and Register Based Memory



Positive Latch Negative Latch



Register Memory



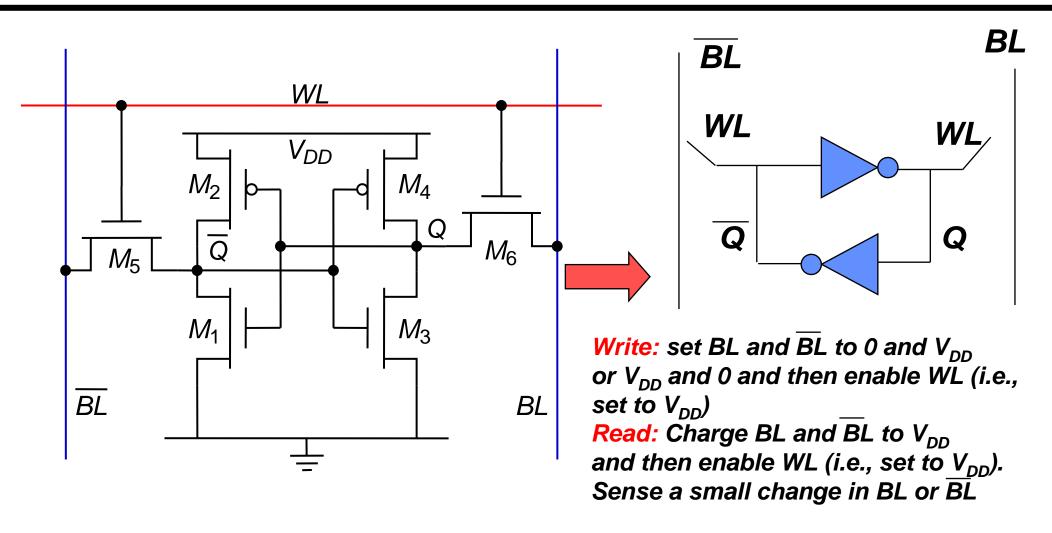
- Works fine for small memory blocks (e.g., small register files)
- Inefficient in area for large memories density is the key metric in large memory circuits

How do we minimize cell size?



Static RAM (SRAM) Cell (The 6-T Cell)



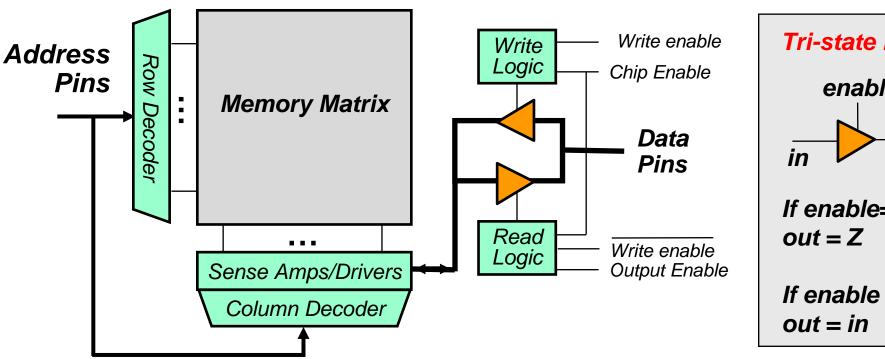


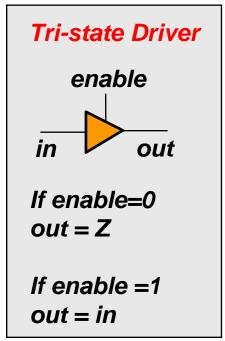
- State held by cross-coupled inverters (M1-M4)
- Static Memory retains state as long as power supply turned on
- Feedback must be overdriven to write into the memory



Interacting with a Memory Device







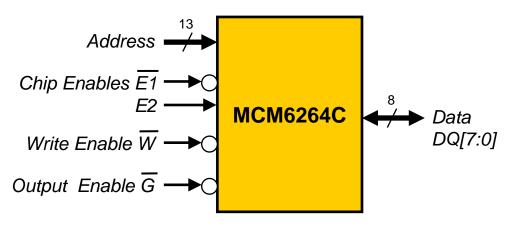
- Address pins drive row and column decoders
- **Data** pins are bidirectional and shared by reads and writes
- **Output Enable** gates the chip's tristate driver
- Write Enable sets the memory's read/write mode
- Chip Enable/Chip Select acts as a "master switch"



MCM6264C 8k x 8 Static RAM

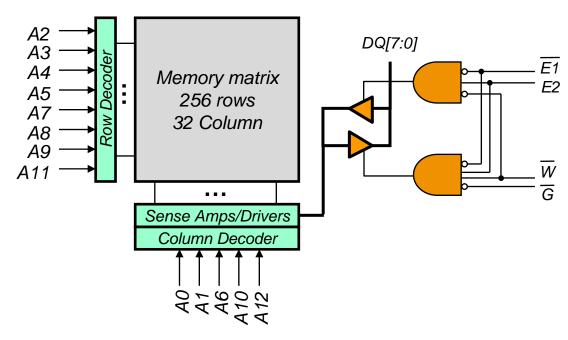


On the outside:

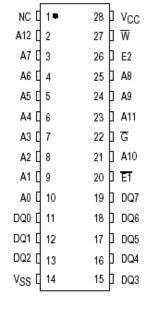


- Same (bidirectional) data bus used for reading and writing
- Chip Enables (E1 and E2)
 - □ E1 must be low and E2 must be high to enable the chip
- Write Enable (W)
 - When low (and chip is enabled), the values on the data bus are written to the location selected by the address bus
- Output Enable (G)
 - □ When low (and chip is enabled with W=0), the data bus is driven with the value of the selected memory location

On the inside:



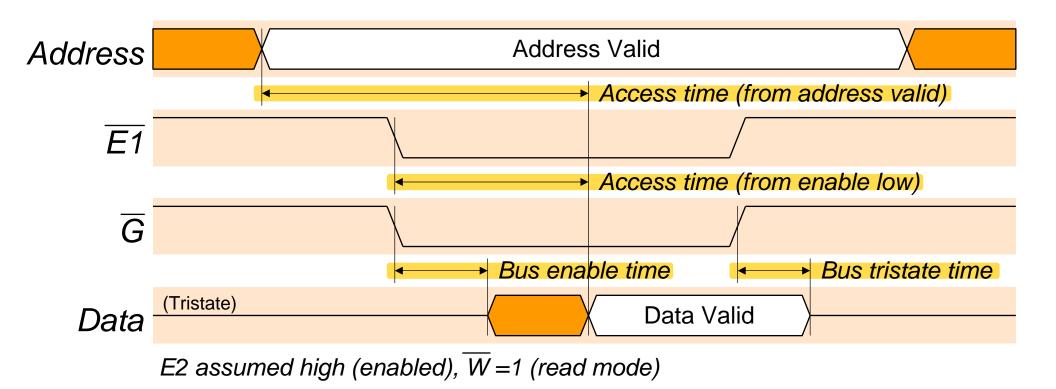
Pinout





Reading an Asynchronous SRAM



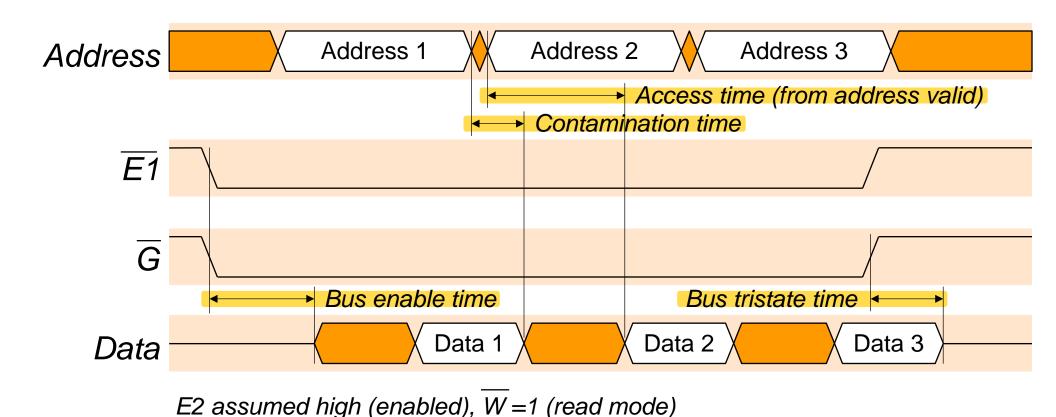


- Read cycle begins when all enable signals (E1, E2, G) are active
- Data is valid after read access time
 - □ Access time is indicated by full part number: MCM6264CP-12 → 12ns
- Data bus is tristated shortly after G or E1 goes high



Address Controlled Reads



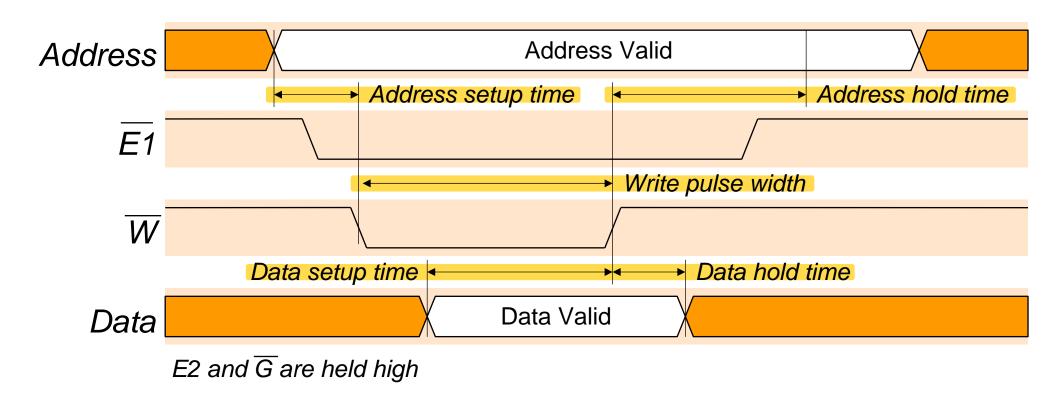


- Can perform multiple reads without disabling chip
- Data bus follows address bus, after some delay



Writing to Asynchronous SRAM



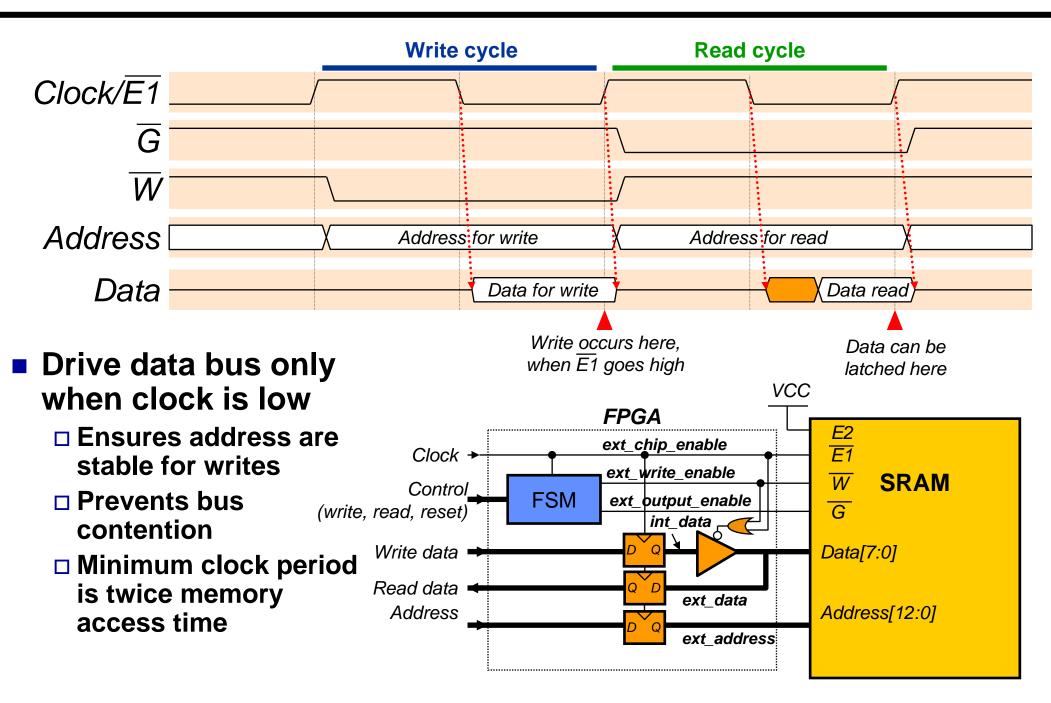


- Data latched when W or E1 goes high (or E2 goes low)
 - □ Data must be stable at this time
 - □ Address must be stable before W goes low
- Write waveforms are more important than read waveforms
 - □ Glitches to address can cause writes to random addresses!



Sample Memory Interface Logic

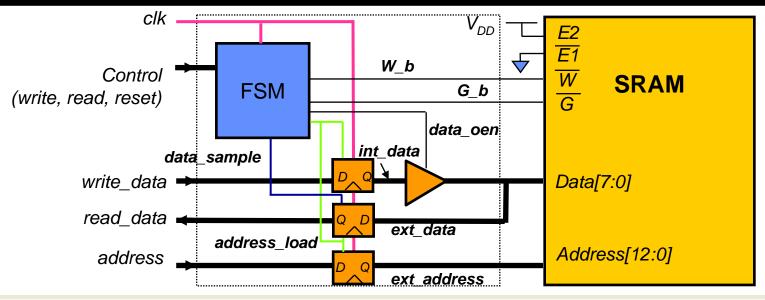


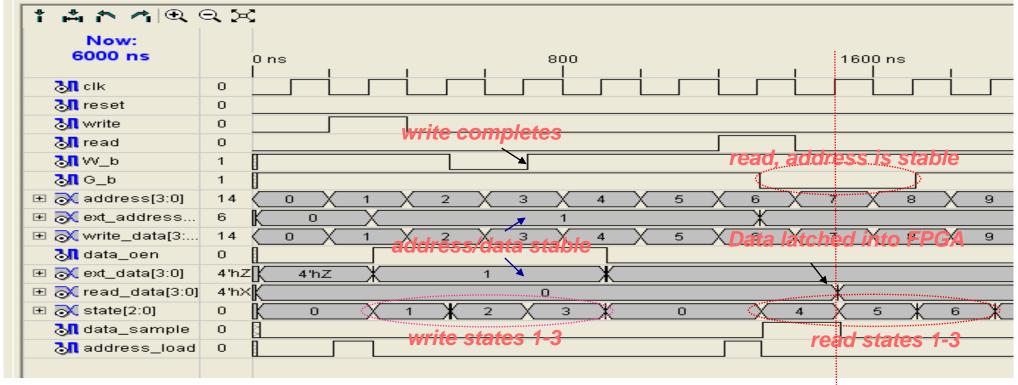




Multi-Cycle Read/Write (less aggressive, recommended timing)



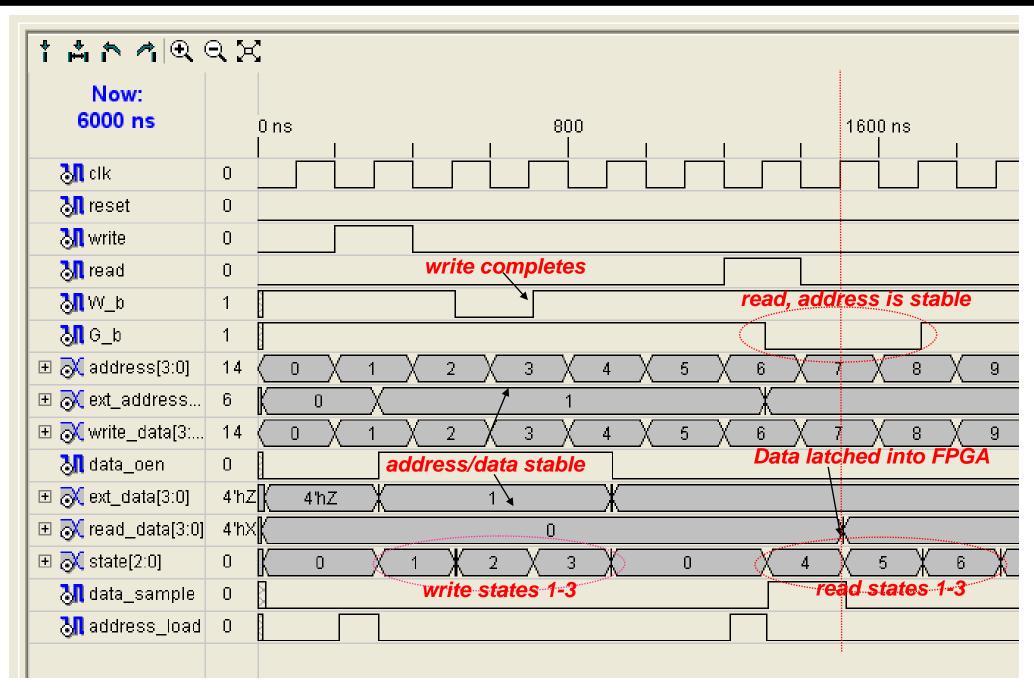






Simulation from Previous Slide







Verilog for Simple Multi-Cycle Access



```
module memtest (clk, reset, G_b, W_b, address, ext_address, write_data, read_data, ext_data, read,
    write, state, data_oen, address_load, data_sample);
 input clk, reset, read, write;
 output G b, W b;
 output [12:0] ext address;
 reg [12:0] ext address;
 input [12:0] address:
 input [7:0] write_data;
 output [7:0] read_data;
 reg [7:0] read data;
 inout [7:0] ext data;
 reg [7:0] int_data;
 output [2:0] state;
 reg [2:0] state, next;
 output data oen, address load, data sample;
 reg G_b, W_b, G_b_int, W_b_int, address_load,
    data_oen, data_oen_int, data_sample;
 wire [7:0] ext_data;
 parameter IDLE = 0;
 parameter write1 = 1;
 parameter write2 = 2;
 parameter write3 = 3;
 parameter read1 = 4;
 parameter read2 = 5;
 parameter read3 = 6;
                                                           1/4
```

```
assign ext_data = data_oen ? int_data : 8'hz;
// Sequential always block for state assignment
always @ (posedge clk)
 begin
 if (!reset) state <= IDLE:
 else state <= next;
 G b \le G b int;
 W b \le W b int;
 data_oen <= data_oen_int;
 if (address_load) ext_address <= address;</pre>
 if (data_sample) read_data <= ext_data;</pre>
 if (address load) int data <= write data;
 end
// note that address load and data sample are not
// registered signals
                                                       2/4
```



Verilog for Simple Multi-Cycle Access



```
// Combinational always block for next-state
// computation
 always @ (state or read or write) begin
   W b int = 1;
   G b int = 1;
                                    Setup the
  address load = 0:
                                 Default values
  data_oen_int = 0;
  data_sample = 0;
  case (state)
   IDLE:
            if (write) begin
                next = write1;
                address_load = 1;
                data_oen_int = 1;
                end
       else if (read) begin
                next = read1;
                address load = 1;
                G_b_{int} = 0;
               end
     else next = IDLE;
   write1: begin
         next = write2:
         W b int = 0;
         data_oen_int =1;
         end
                                                       3/4
```

```
write2: begin
         next = write3;
         data_oen_int =1;
         end
  write3: begin
         next = IDLE;
         data oen int = 0;
         end
  read1: begin
         next = read2;
         G_b_{int} = 0;
         data sample = 1;
         end
  read2: begin
         next = read3:
         end
  read3: begin
         next = IDLE;
         end
   default: next = IDLE:
  endcase
 end
endmodule
                                                    4/4
```



Testing Memories



Common device problems

- □ Bad locations: rare for individual locations to be bad
- ☐ Slow (out-of-spec) timing(s): access incorrect data or violates setup/hold
- ☐ Catastrophic device failure: e.g., ESD
- ☐ Missing wire-bonds/devices (!): possible with automated assembly
- ☐ Transient Failures: Alpha particles, power supply glitch

Common board problems

- □ Stuck-at-Faults: a pin shorted to V_{DD} or GND
- □ Open Circuit Fault: connections unintentionally left out
- □ Open or shorted address wires: causes data to be written to incorrect locations
- Open or shorted control wires: generally renders memory completely inoperable

Approach

- □ Device problems generally affect the entire chip, almost any test will detect them
- Writing (and reading back) many different data patterns can detect data bus problems
- □ Writing unique data to every location and then reading it back can detect address bus problems

Mit

An Approach

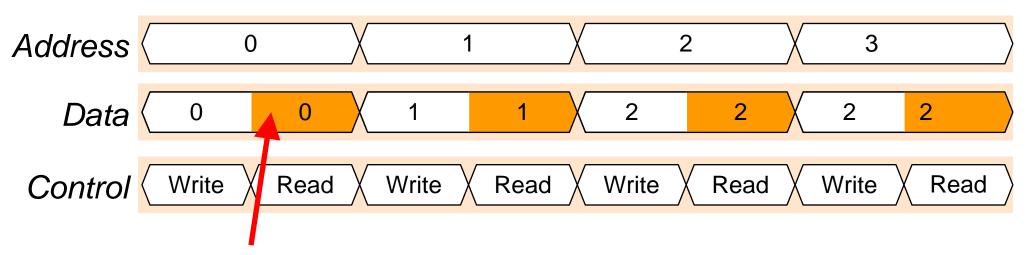


An idea that almost works

- 1. Write 0 to location 0
- 2. Read location 0, compare value read with 0
- 3. Write 1 to location 1
- 4. Read location 1, compare value read with 1
- 5. ...

What is the problem?

Suppose the memory was missing (or output enable was disconnected)



Data bus is undriven but wire capacitance briefly maintains the bus state: memory appears to be ok!

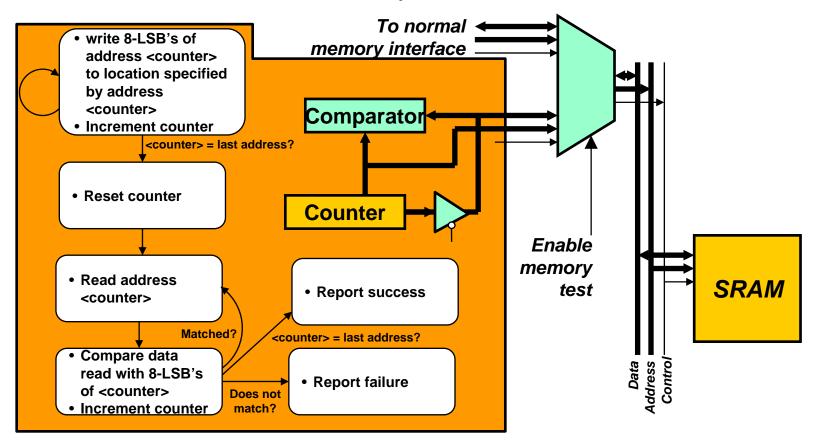


A Simple Memory Tester



- Write to all locations, then read back all locations
 - □ Separates read/write to the same location with reads/writes of different data to different locations
 - □ (both data and address busses are changed between read and write to same location)

- Write 0 to address 0
- Write 1 to address 1
- ..
- Write (n mod 256) to address n
- Read address 0, compare with 0
- Read address 1, compare with 1
- ...
- Read address n, compare with (n mod 256)

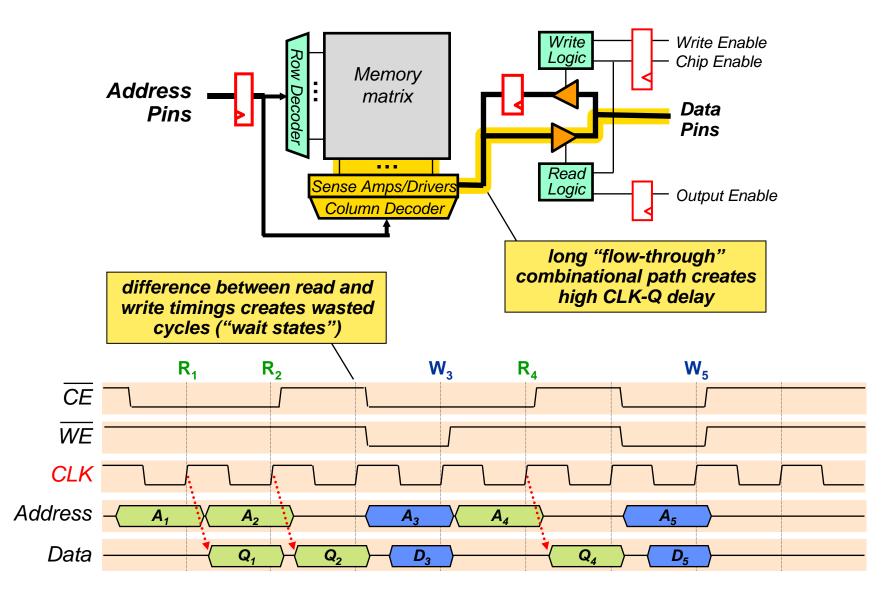




Synchronous SRAM Memories



 Clocking provides input synchronization and encourages more reliable operation at high speeds

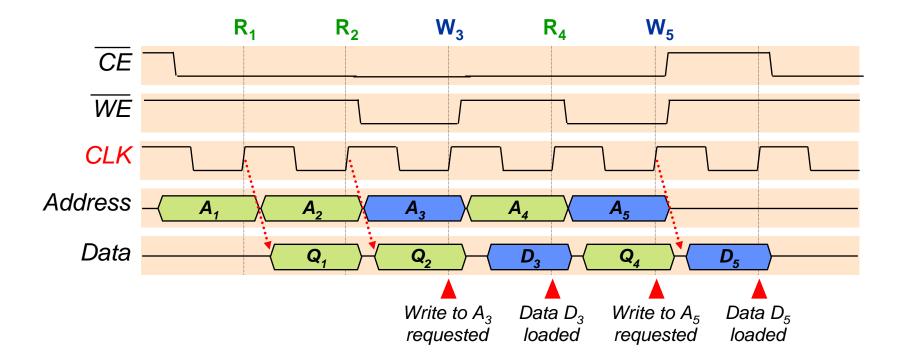




ZBT Eliminates the Wait State



- The wait state occurs because:
 - □ On a read, data is available after the clock edge
 - □ On a write, data is set up *before* the clock edge
- ZBT ("zero bus turnaround") memories change the rules for writes
 - On a write, data is set up after the clock edge (so that it is read on the following edge)
 - □ Result: no wait states, higher memory throughput

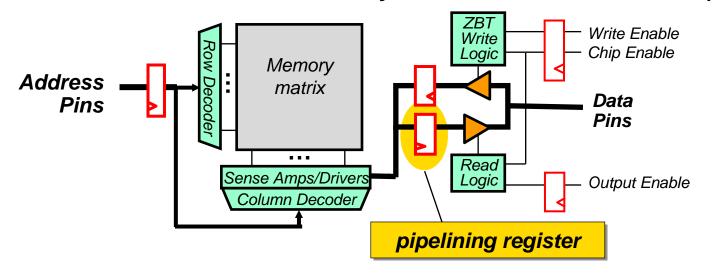




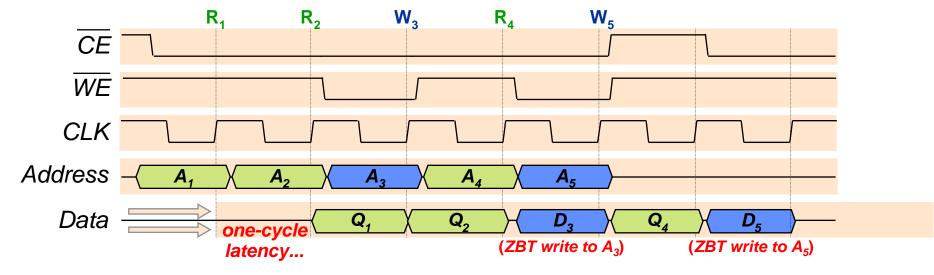
Pipelining Allows Faster CLK



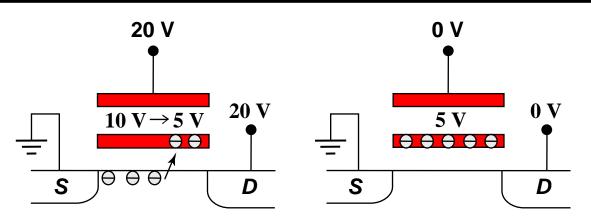
- Pipeline the memory by registering its output
 - □ Good: Greatly reduces CLK-Q delay, allows higher clock (more throughput)
 - □ Bad: Introduces an extra cycle before data is available (more latency)



As an example, see the CY7C147X ZBT Synchronous SRAM

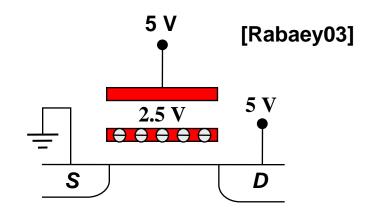


Illii EPROM Cell – The Floating Gate Transistor Illii

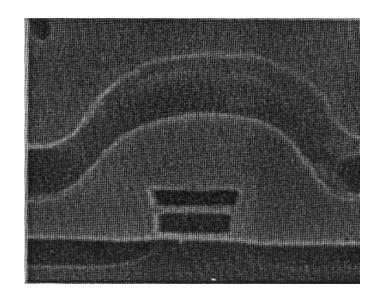




Removing programming voltage leaves charge trapped



Programming results in higher V_T .



EPROM Cell

Courtesy Intel

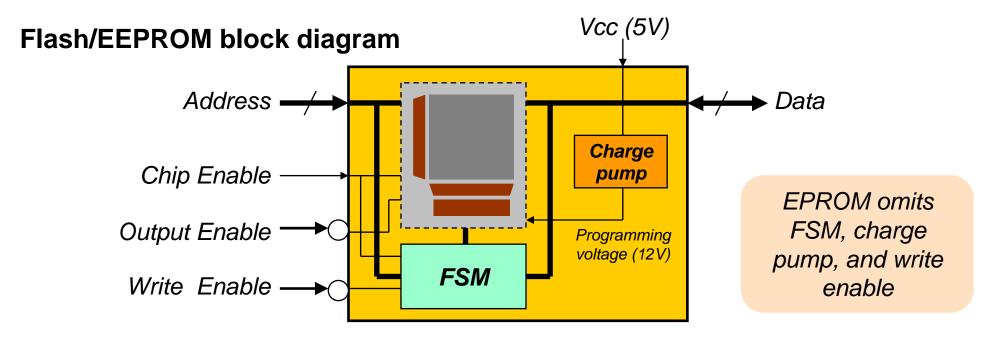
This is a non-volatile memory (retains state when supply turned off)



Interacting with Flash and (E)EPROM



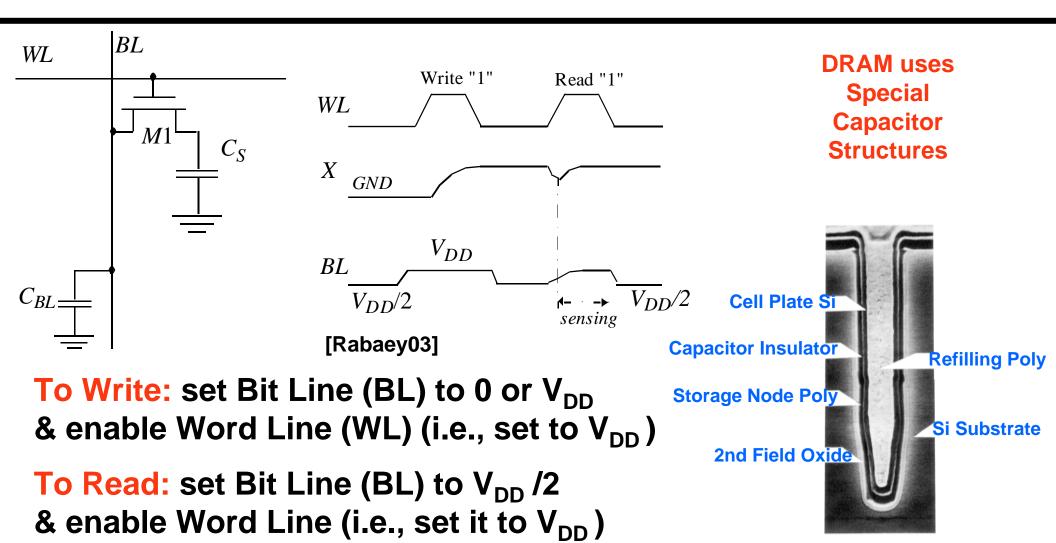
- Reading from flash or (E)EPROM is the same as reading from SRAM
- Vpp: input for programming voltage (12V)
 - □ EPROM: Vpp is supplied by programming machine
 - □ Modern flash/EEPROM devices generate 12V using an on-chip charge pump
- EPROM lacks a write enable
 - □ Not in-system programmable (must use a special programming machine)
- For flash and EEPROM, write sequence is controlled by an internal FSM
 - □ Writes to device are used to send signals to the FSM
 - □ Although the same signals are used, one can't write to flash/EEPROM in the same manner as SRAM





Dynamic RAM (DRAM) Cell



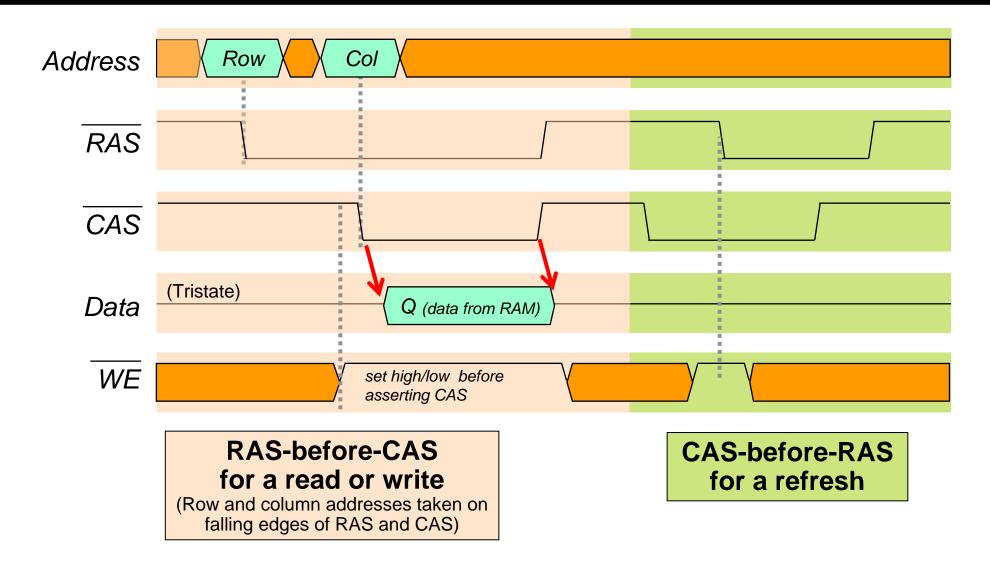


- DRAM relies on charge stored in a capacitor to hold state
- Found in all high density memories (one bit/transistor)
- Must be "refreshed" or state will be lost high overhead



Asynchronous DRAM Operation





 Clever manipulation of RAS and CAS after reads/writes provide more efficient modes: early-write, read-write, hidden-refresh, etc. (See datasheets for details)



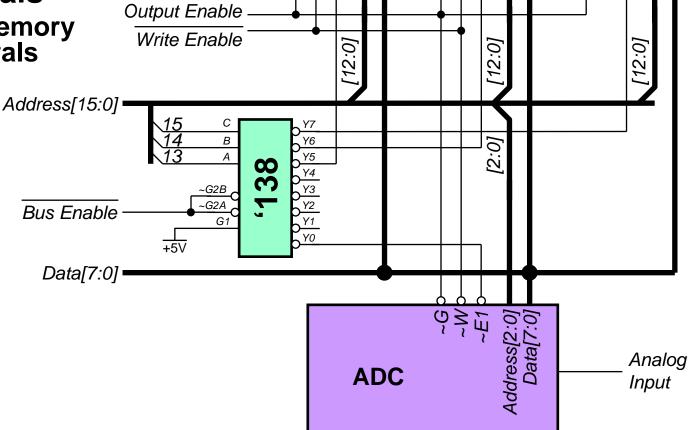
Addressing with Memory Maps



EPROM



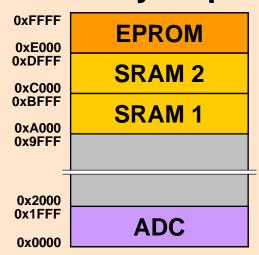
- Maps 16-bit address space to 8, 13-bit segments
- Upper 3-bits of address determine which chip is enabled
- SRAM-like interface is often used for peripherals
 - □ Referred to as "memory mapped" peripherals



SRAM 1

SRAM 2

Memory Map





Key Messages on Memory Devices



SRAM vs. DRAM

- □ SRAM holds state as long as power supply is turned on. DRAM must be "refreshed" results in more complicated control
- DRAM has much higher density, but requires special capacitor technology.
- □ FPGA usually implemented in a standard digital process technology and uses SRAM technology

Non-Volatile Memory

- □ Fast Read, but very slow write (EPROM must be removed from the system for programming!)
- □ Holds state even if the power supply is turned off

Memory Internals

Has quite a bit of analog circuits internally -- pay particular attention to noise and PCB board integration

Device details

□ Don't worry about them, wait until 6.012 or 6.374



You Should Understand Why...



- control signals such as Write Enable should be registered
- a multi-cycle read/write is safer from a timing perspective than the single cycle read/write approach
- it is a bad idea to enable two tri-states driving the bus at the same time
- an SRAM does not need to be "refreshed" while a DRAM does
- an EPROM/EEPROM/FLASH cell can hold its state even if the power supply is turned off
- a synchronous memory can result in higher throughput